

Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	-50	V
Drain-Gate Voltage $R_{GS} \le 20k\Omega$		V_{DGR}	-50	V
Gate-Source Voltage	Continuous	V_{GSS}	±20	V
Drain Current (Note 5)	Continuous	Ι _D	-130	mA
Pulsed Drain Current		I _{DM}	-1.2	A

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_{D}	300	mW
Thermal Resistance, Junction to Ambient	$R_{ hetaJA}$	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

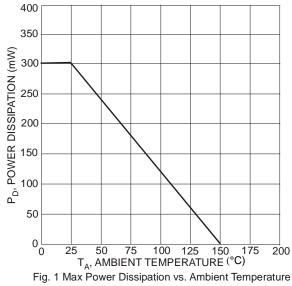
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV _{DSS}	-50	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
		_	_	-1	μA	$V_{DS} = -50V$, $V_{GS} = 0V$, $T_{J} = +25$ °C	
Zero Gate Voltage Drain Current	I_{DSS}	_	_	-2	μΑ	$V_{DS} = -50V$, $V_{GS} = 0V$, $T_{J} = +125$ °C	
		_	—	-100	nA	$V_{DS} = -25V$, $V_{GS} = 0V$, $T_{J} = +25$ °C	
Gate-Body Leakage	I _{GSS}	_	_	±10	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	$V_{GS(TH)}$	-0.8	_	-2.0	V	$V_{DS} = V_{GS}$, $I_D = -1mA$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	_	10	Ω	$V_{GS} = -5V, I_D = -0.100A$	
Forward Transconductance	g FS	0.05	_	_	S	$V_{DS} = -25V, I_{D} = -0.1A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C _{iss}	_	24.6	45	pF		
Output Capacitance	Coss	_	4.7	25	pF	$V_{DS} = -25V$, $V_{GS} = 0V$, $f = 1.0MHz$	
Reverse Transfer Capacitance	C _{rss}	_	2.8	12	pF		
Gate Resistance	R_g	_	916	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Q_g	_	0.28	_	nC	V _{DS} = -10V, I _D = -0.1A	
Total Gate Charge (V _{GS} = -10V)	Qg	_	0.59	_	nC		
Gate-Source Charge	Qgs	_	0.09	_	nC		
Gate-Drain Charge	Q_{gd}	_	0.08	_	nC		
Turn-On Delay Time	t _{D(ON)}	_	10	_	ns	$V_{DD} = -30V$, $I_D = -0.27A$,	
Turn-Off Delay Time	t _{D(OFF)}		18	_	ns	$R_{GEN} = 50\Omega$, $V_{GS} = -10V$	

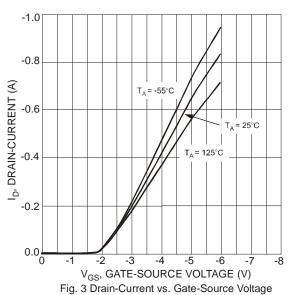
Notes: 5. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at http://www.diodes.com/package-outlines.html.

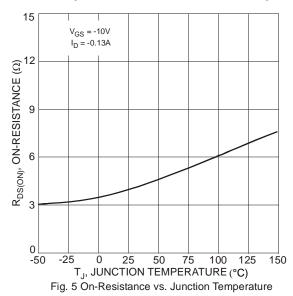
^{6.} Short duration pulse test used to minimize self-heating effect.

^{7.} Guaranteed by design. Not subject to production testing.









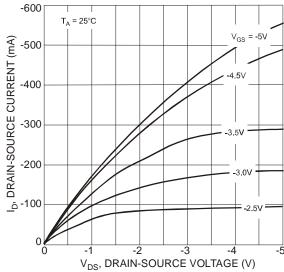


Fig. 2 Drain-Source Current vs. Drain-Source Voltage

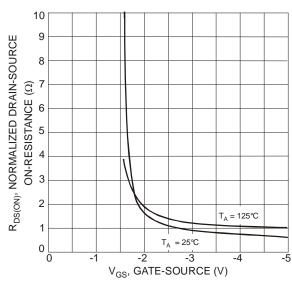


Fig. 4 On-Resistance vs. Gate-Source Voltage

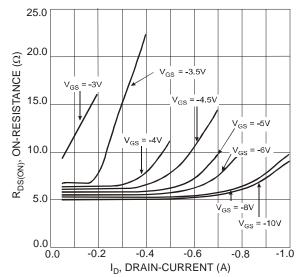


Fig. 6 On-Resistance vs. Drain-Current





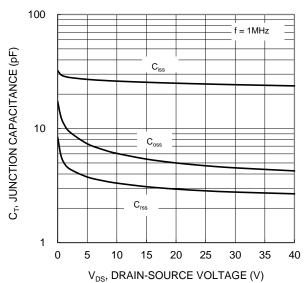
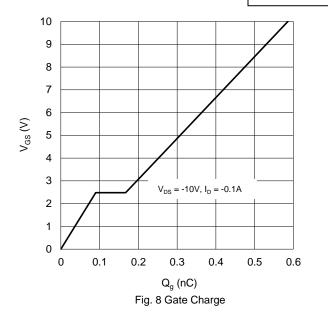


Fig. 7 Typical Junction Capacitance 10 R_{DS(ON)} Limited ID, DRAIN CURRENT (A) 1 0.1 P_W = 100ms $T_{J(Max)} = 150$ °C $T_C = 25$ °C Single Pulse DUT on 1*MRP 0.01 Board V_{GS} = -10V 0.001 0.1 1 10

100

 V_{DS} , DRAIN-SOURCE VOLTAGE (V) Fig. 9 SOA, Safe Operation Area

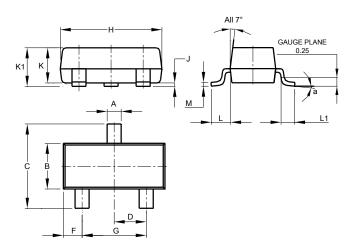




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

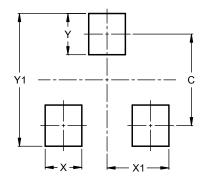


SOT23				
Dim	Min	Max	Тур	
Α	0.37	0.51	0.40	
В	1.20	1.40	1.30	
C	2.30	2.50	2.40	
D	0.89	1.03	0.915	
F	0.45	0.60	0.535	
G	1.78	2.05	1.83	
Η	2.80	3.00	2.90	
J	0.013	0.10	0.05	
K	0.890	1.00	0.975	
K1	0.903	1.10	1.025	
L	0.45	0.61	0.55	
L1	0.25	0.55	0.40	
М	0.085	0.150	0.110	
а	0°	8°		
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



Dimensions	Value (in mm)		
С	2.0		
Х	0.8		
X1	1.35		
Y	0.9		
Y1	29		



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